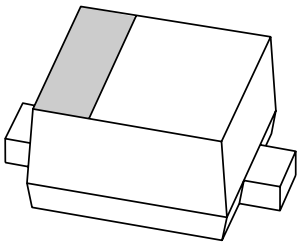
DATA SHEET



BAP70-02
Silicon PIN diode

Product specification
Supersedes data of 2002 Jul 02

2002 Aug 06

Philips
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PHILIPS

Silicon PIN diode BAP70-02

FEATURES

- High voltage, current controlled RF resistor for attenuators
- Low diode capacitance
- Very low series inductance.

APPLICATIONS

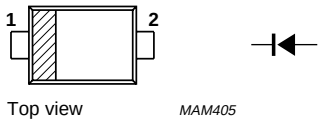
- RF attenuators
- (SAT)TV
- Car radio.

DESCRIPTION

Planar PIN diode in a SOD523 ultra small SMD plastic package.

PINNING

PIN	DESCRIPTION
1	cathode
2	anode



Marking code: K8.

Fig.1 Simplified outline (SOD523) and symbol.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_R	continuous reverse voltage		–	50	V
I_F	continuous forward current		–	100	mA
P_{tot}	total power dissipation	T_s = 90 °C	–	415	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–65	+150	°C

ELECTRICAL CHARACTERISTICS

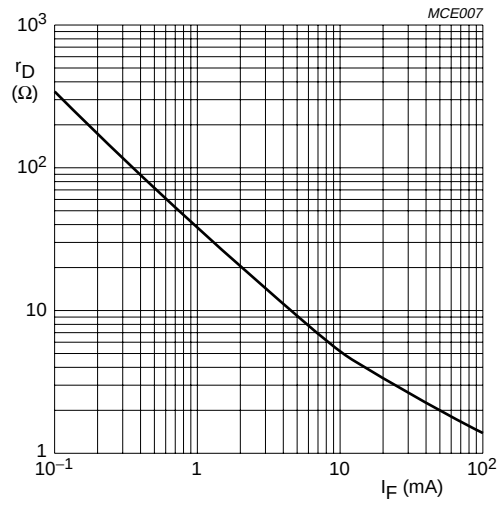
T_j = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V_F	forward voltage	I_F = 50 mA	0.9	1.1	V
I_R	reverse leakage current	V_R = 50 V	–	20	nA
C_d	diode capacitance	V_R = 0 V; f = 1 MHz	570	–	fF
		V_R = 1 V; f = 1 MHz	400	–	fF
		V_R = 5 V; f = 1 MHz	270	–	fF
		V_R = 20 V; f = 1 MHz	200	250	fF
r_D	diode forward resistance	I_F = 0.5 mA; f = 100 MHz	77	100	Ω
		I_F = 1 mA; f = 100 MHz	40	50	Ω
		I_F = 10 mA; f = 100 MHz	5.4	7	Ω
		I_F = 100 mA; f = 100 MHz	1.4	1.9	Ω
τ_L	charge carrier life time	when switched from I_F = 10 mA to I_R = 6 mA; R_L = 100 Ω; measured at I_R = 3 mA	1.25	–	µs
L_S	series inductance	I_F = 100 mA; f = 100 MHz	0.6	–	nH

THERMAL CHARACTERISTICS

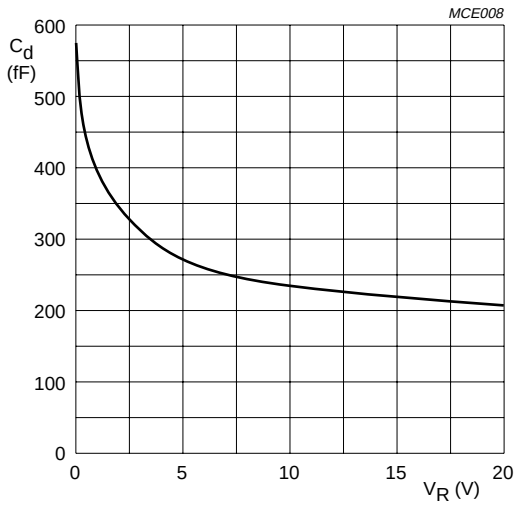
SYMBOL	PARAMETER	VALUE	UNIT
$R_{th\ j\text{-}s}$	thermal resistance from junction to soldering point	145	K/W

GRAPHICAL DATA



f = 100 MHz; T_j = 25 °C.

Fig.2 Forward resistance as a function of forward current; typical values.

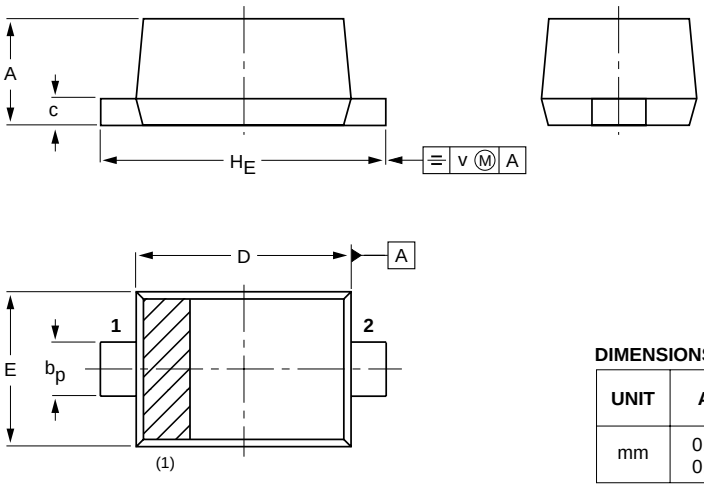


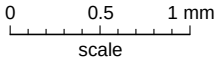
f = 1 MHz; T_j = 25 °C.

Fig.3 Diode capacitance as a function of reverse voltage; typical values.

PACKAGE OUTLINE

Plastic surface mounted package; 2 leads **SOD523**





DIMENSIONS (mm are the original dimensions)

UNIT	A	b_p	c	D	E	H_E	v
mm	0.7 0.5	0.35 0.25	0.2 0.1	1.3 1.1	0.9 0.7	1.7 1.5	0.15

Note

1. The marking bar indicates the cathode.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOD523			SC-79			98-11-25

DATA SHEET STATUS

DATA SHEET STATUS[1]	PRODUCT STATUS[2]	DEFINITIONS
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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Printed in The Netherlands 613516/03/pp8 Date of release: 2002 Aug 06 Document order number: 9397 750 10093

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